

an array of wire bond connections on the die electrically connected to the solder ball array connections;

wherein known good die testing is completed prior to mounting the known good die on an end use device by connecting a test device by wire bond connections or by solder ball connections;

wherein when either the wire bond connections are used or the solder ball connections are used for known good die testing, the other is available for connection to an end use device.

2. (Amended) The known good die in accordance with claim 1, wherein when either the wire bond connections or stress tolerant solder ball connections is used to form a contact with the test device, the other is not affected by a known good die (KGD) test.

3. (Amended) The known good die in accordance with claim 1, wherein the wire bond connections and the solder ball array connections are on the same side of the die.

4. (Amended) The known good [integrated circuit device] die in accordance with claim 1, wherein the solder ball array connections and the wire bond connections are on the substantially the same level of the integrated circuit so that either may provide contact with an end use device.

5. (Amended) The known good die in accordance with claim 1, wherein the solder ball array connections or wire bond connections

which are used for testing are not removed from the die after testing.

B2
6. (Amended) The known good die in accordance with claim 1, wherein connections to the test device are metallurgical connections.

7. (Amended) The known good die in accordance with claim 1, wherein the solder ball array connections are controlled collapse chip connections.

8. (Amended) The known good die in accordance with claim 1, wherein the solder ball array forming the solder ball array connections is a stress tolerant solder ball array.

B3
10. (Amended) The known good die in accordance with claim 1 wherein the known good die is connected to an end use device.

Please add new claim 44 as follows:

B4
44. (New) The known good die in accordance with claim 10, wherein the connections used for known good die testing are no longer useful when the known good die is placed in an end use device.